UPDATE CHANGE NOTIFICATION # 16949

Generic Copy

Issue Date: 30-Jan-2013

TITLE: Update to Final Notification of Transfer of product ESD1014MUTAG from ON Semiconductor Sanyo Fab in Gunma (Japan) to ON Semiconductor Fab10 in Pocatello (USA).

PROPOSED FIRST SHIP DATE: 11-Mar-2013

AFFECTED CHANGE CATEGORY(S): Changed Part Identification

ADDITIONAL RELIABILITY DATA: N/A

SAMPLES: Contact your local ON Semiconductor Sales Office

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or <Jacob.Saliba@onsemi.com>

NOTIFICATION TYPE:

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

FPCN #16949 announced that ON Semiconductor is transferring product ESD1014MUTAG from ON Semiconductor Sanyo Fab in Gunma (Japan) to ON Semiconductor Fab10 in Pocatello (USA).

FPCN #16949 omitted the part identification that marks the transition to the new Fab10 die.

This PCN will serve to clarify this omission.

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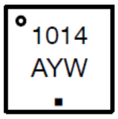
CHANGED PART IDENTIFICATION:

UDFN10
CASE 517AN

MARKING
DIAGRAM



1014 = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
▪ = Pb−Free Package

The Fab10 die will be utilized on all ESD1014 built on or after date code:

1014
RYJ

List of affected General Parts:

ESD1014MUTAG